

# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Ta-Hsun Yeh	10/03/2006
Yuh-Sheng Jean	10/03/2006
RECEIVING PARTY DATA	
Name:	Realtek Semiconductor Corp.
Street Address:	2 Innovation Rd. II, Science Park
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State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11548687
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ATTORNEY DOCKET NUMBER:	REAP0228USA
NAME OF SUBMITTER:	WINSTON HSU
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REEL: 018379 FRAME: 0032

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Ta-Hsun Yeh Nationality: R.O.C.

Address: No. 40, Tse-Fan Rd., Hsin-Chu City, Taiwan, R.O.C.

Name: Yuh-Sheng Jean Nationality: R.O.C.

Address: No. 72-2, Songdong Rd., Songzhu Village, Dapi Hsiang, Yun-Lin Hsien, Taiwan, R.O.C.

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: Realtek Semiconductor Corp.

Address: 2 Innovation Rd. II, Science Park, HsinChu 30076, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

**" INTEGRATED INDUCTOR "**

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this OCT. 03 2006 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Ta-Hsun Yeh

Yuh-Sheng Jean

Signature of INVENTOR

Ta-Hsun Yeh  
Yuh-Sheng Jean